

2814



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : *Weber*
Serial No. : 09/898,909
Filed : July 3, 2001
Title : METALLIZATION ARRANGEMENT FOR SEMICONDUCTOR STRUCTURE
AND CORRESPONDING FABRICATION METHOD

Art Unit : 2814
Examiner : P. Cao

Commissioner for Patents
Washington, D.C. 20231

#11/B
marsha
4/23/03


REPLY

In reply to the action mailed January 16, 2003, please amend the application as indicated on the following pages. Applicant asks that all claims be allowed in view of the amendment to the claims and remarks contained on the following sheets, a total of six pages.

No additional fees are believed to be due in connection with the filing of this response. However, to the extent fees are due, or if a refund is forthcoming, please adjust our Deposit Account No. 06-1050.

Respectfully submitted,

Date: April 15, 2003


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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

April 15, 2003
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